



ALPHA & OMEGA
SEMICONDUCTOR

AOK20B120E2

1200V, 20A Alpha IGBT™

With soft and fast recovery anti-parallel diode

General Description

- Latest Alpha IGBT (α IGBT) technology
- Best in Class $V_{CE(sat)}$ enables high efficiencies
- Low turn-off switching loss due to fast turn-off time
- Very smooth turn-off current waveforms reduce EMI
- Better thermal management
- High surge current capability
- Minimal gate spike due to high input capacitance

Product Summary

V_{CE}	1200V
I_C ($T_C=100^\circ C$)	20A
$V_{CE(sat)}$ ($T_C=25^\circ C$)	1.75V

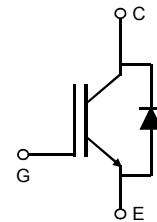
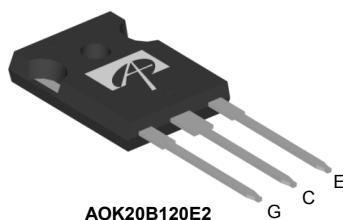
Applications

- Induction Cooking
- Rice Cookers
- Microwave Ovens
- Other soft switching applications



Top View

TO-247



Orderable Part Number	Package Type	Form	Minimum Order Quantity
AOK20B120E2	TO247	Tube	240

Absolute Maximum Ratings $T_A=25^\circ C$ unless otherwise noted

Parameter	Symbol	AOK20B120E2	Units
Collector-Emitter Voltage	V_{CE}	1200	V
Gate-Emitter Voltage	V_{GE}	± 30	V
Continuous Collector Current $T_C=25^\circ C$	I_C	40	A
$T_C=100^\circ C$		20	
Pulsed Collector Current, Limited by T_{Jmax}	I_{Cpulse}	80	A
Non repetitive peak collector current ^A	I_{CSM}	200	A
Turn off SOA, $V_{CE} \leqslant 600V$, Limited by T_{Jmax}	I_{LM}	80	A
Continuous Diode Forward Current $T_C=25^\circ C$	I_F	40	A
$T_C=100^\circ C$		20	
Diode Pulsed Current, Limited by T_{Jmax}	I_{Fpulse}	80	A
Power Dissipation $T_C=25^\circ C$	P_D	250	W
$T_C=100^\circ C$		125	
Junction and Storage Temperature Range	T_J, T_{STG}	-55 to 175	°C
Maximum lead temperature for soldering purpose, 1/8" from case for 5 seconds	T_L	300	°C
Thermal Characteristics			
Parameter	Symbol	AOK20B120E2	Units
Maximum Junction-to-Ambient	$R_{\theta JA}$	40	°C/W
Maximum IGBT Junction-to-Case	$R_{\theta JC}$	0.6	°C/W
Maximum Diode Junction-to-Case	$R_{\theta DC}$	1.6	°C/W

Note A: Capacitor charging saturation current limited by $T_{jmax}<175^\circ C$ and $t_p<3\mu s$

Electrical Characteristics ($T_J=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
STATIC PARAMETERS						
BV_{CES}	Collector-Emitter Breakdown Voltage	$I_C=1\text{mA}, V_{GE}=0\text{V}, T_J=25^\circ\text{C}$	1200	-	-	V
$V_{CE(sat)}$	Collector-Emitter Saturation Voltage	$V_{GE}=15\text{V}, I_C=20\text{A}$	$T_J=25^\circ\text{C}$	-	1.75	2.2
			$T_J=125^\circ\text{C}$	-	2.2	-
			$T_J=175^\circ\text{C}$	-	2.3	-
V_F	Diode Forward Voltage	$V_{GE}=0\text{V}, I_C=20\text{A}$	$T_J=25^\circ\text{C}$	-	1.6	2
			$T_J=125^\circ\text{C}$	-	2.3	-
			$T_J=175^\circ\text{C}$	-	2.4	-
$V_{GE(th)}$	Gate-Emitter Threshold Voltage	$V_{CE}=5\text{V}, I_C=1\text{mA}$	4.4	5.05	5.7	V
I_{CES}	Zero Gate Voltage Collector Current	$V_{CE}=1200\text{V}, V_{GE}=0\text{V}$	$T_J=25^\circ\text{C}$	-	-	10
			$T_J=125^\circ\text{C}$	-	-	500
			$T_J=175^\circ\text{C}$	-	-	5000
I_{GES}	Gate-Emitter leakage current	$V_{CE}=0\text{V}, V_{GE}=\pm 30\text{V}$	-	-	± 100	nA
g_{FS}	Forward Transconductance	$V_{CE}=20\text{V}, I_C=20\text{A}$	-	22.5	-	S
DYNAMIC PARAMETERS						
C_{ies}	Input Capacitance	$V_{GE}=0\text{V}, V_{CE}=25\text{V}, f=1\text{MHz}$	-	1445	-	pF
C_{oes}	Output Capacitance		-	85	-	pF
C_{res}	Reverse Transfer Capacitance		-	25	-	pF
Q_g	Total Gate Charge	$V_{GE}=15\text{V}, V_{CE}=960\text{V}, I_C=20\text{A}$	-	53.5	-	nC
Q_{ge}	Gate to Emitter Charge		-	12	-	nC
Q_{gc}	Gate to Collector Charge		-	24.5	-	nC
R_g	Gate resistance	$V_{GE}=0\text{V}, V_{CE}=0\text{V}, f=1\text{MHz}$	-	2.2	-	Ω
SWITCHING PARAMETERS, (Load Inductive, $T_J=25^\circ\text{C}$)						
$t_{D(off)}$	Turn-Off Delay Time	$T_J=25^\circ\text{C}$ $V_{GE}=15\text{V}, V_{CE}=600\text{V}, I_C=20\text{A}, R_G=15\Omega,$ Parasitic Inductance=150nH	-	123	-	ns
t_f	Turn-Off Fall Time		-	120	-	ns
E_{off}	Turn-Off Energy		-	0.82	-	mJ
SWITCHING PARAMETERS, (Load Inductive, $T_J=175^\circ\text{C}$)						
$t_{D(off)}$	Turn-Off Delay Time	$T_J=175^\circ\text{C}$ $V_{GE}=15\text{V}, V_{CE}=600\text{V}, I_C=20\text{A}, R_G=15\Omega,$ Parasitic Inductance=150nH	-	144	-	ns
t_f	Turn-Off Fall Time		-	170	-	ns
E_{off}	Turn-Off Energy		-	1.32	-	mJ

THIS PRODUCT HAS BEEN DESIGNED AND QUALIFIED FOR THE CONSUMER MARKET. APPLICATIONS OR USES AS CRITICAL
COMPONENTS IN LIFE SUPPORT DEVICES OR SYSTEMS ARE NOT AUTHORIZED. AOS DOES NOT ASSUME ANY LIABILITY ARISING
OUT OF SUCH APPLICATIONS OR USES OF ITS PRODUCTS. AOS RESERVES THE RIGHT TO IMPROVE PRODUCT DESIGN,
FUNCTIONS AND RELIABILITY WITHOUT NOTICE.

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

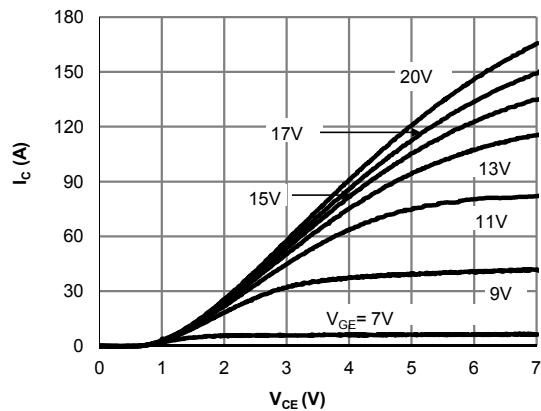


Figure 1: Output Characteristic
($T_j=25^\circ\text{C}$)

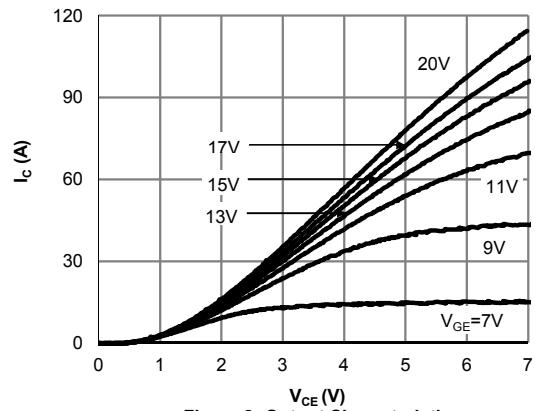


Figure 2: Output Characteristic
($T_j=175^\circ\text{C}$)

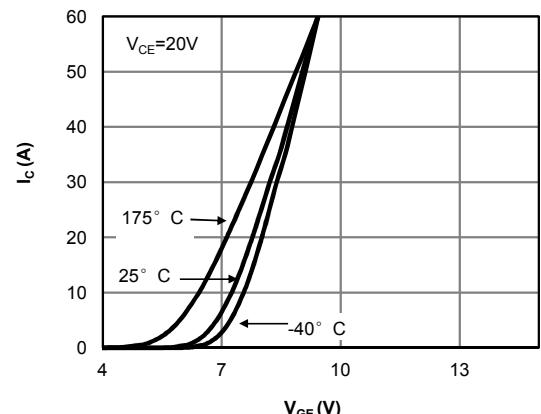


Figure 3: Transfer Characteristic
 $V_{CE}=20\text{V}$

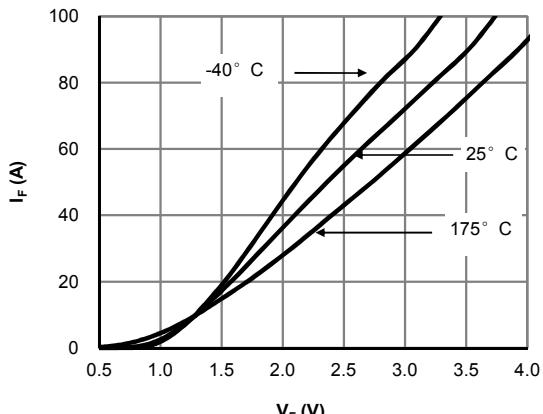


Figure 4: Diode Characteristic

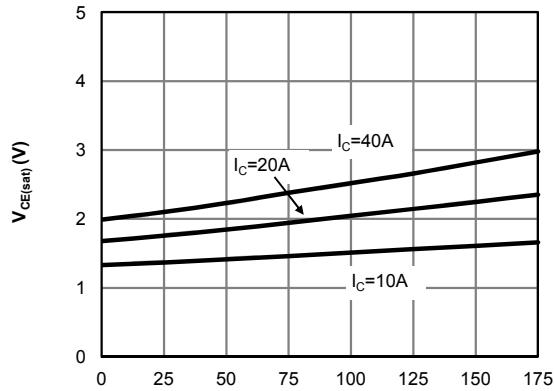


Figure 5: Collector-Emitter Saturation Voltage vs.
Junction Temperature

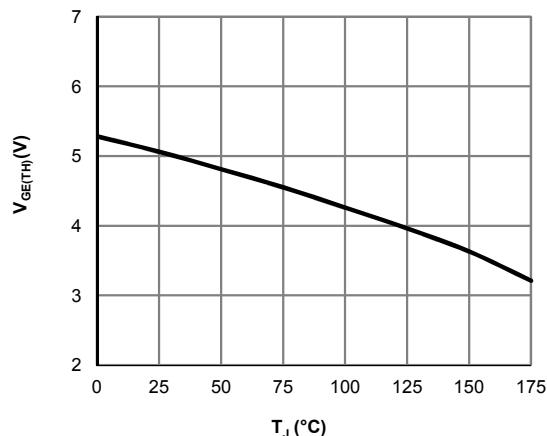


Figure 6: $V_{GE(\text{TH})}$ vs. T_j

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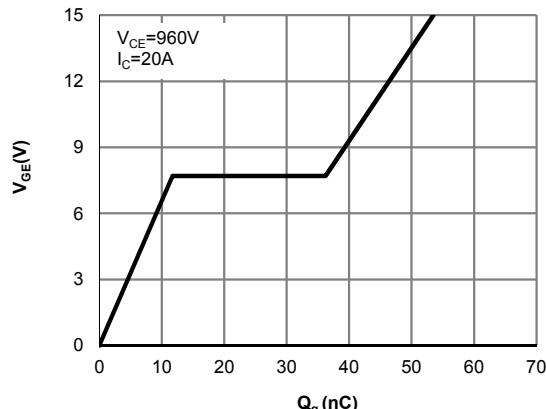


Figure 7: Gate-Charge Characteristics

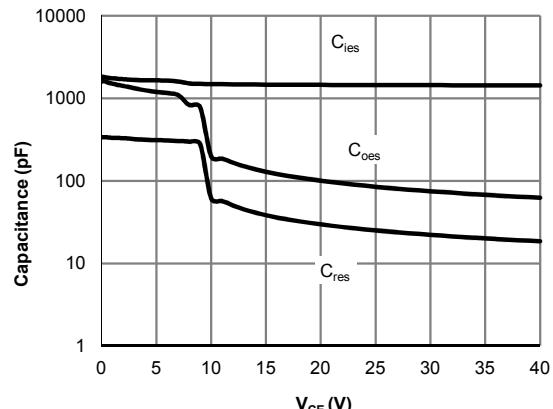


Figure 8: Capacitance Characteristic

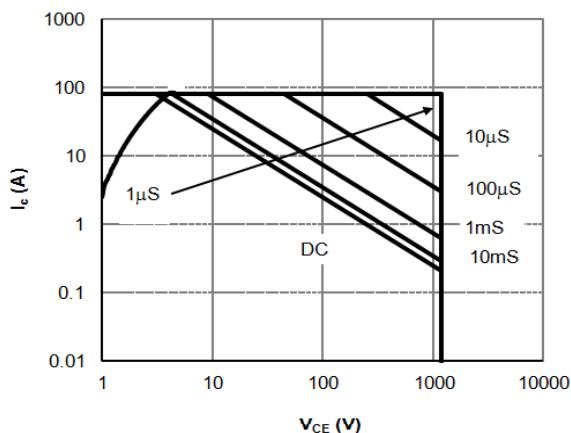
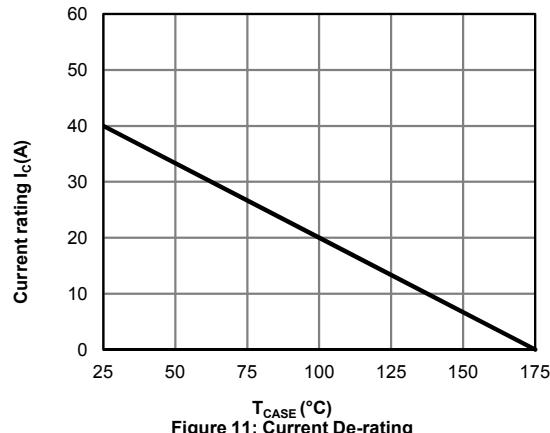
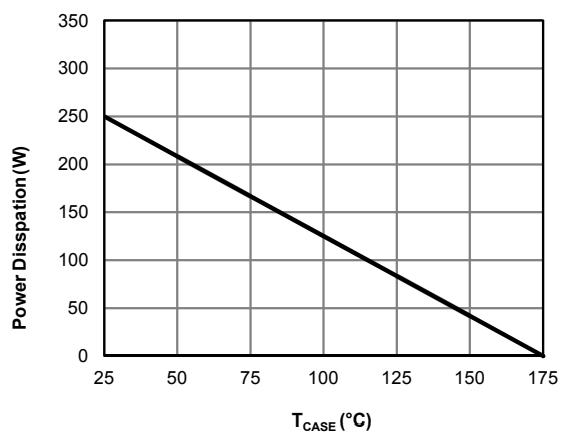


Figure 9: Forward Bias Safe Operating Area
 $(T_C=25^\circ C, V_{GE}=15V)$



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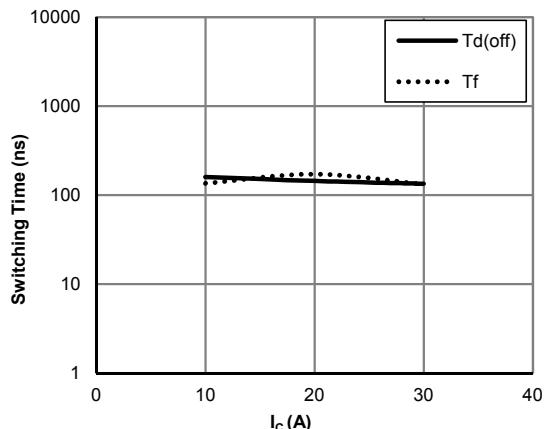


Figure 12: Switching Time vs. I_c
(T_j=175°C, V_{GE}=15V, V_{CE}=600V, R_g=15Ω)

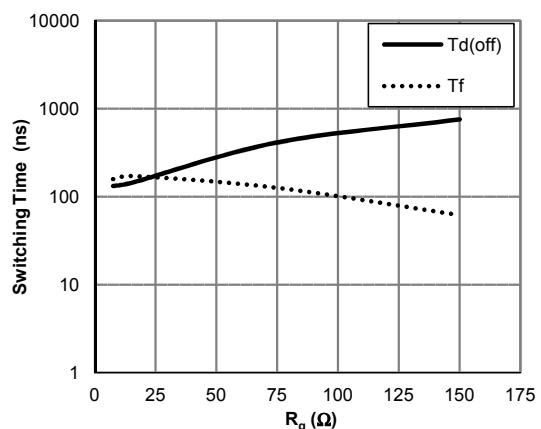


Figure 13: Switching Time vs. R_g
(T_j=175°C, V_{GE}=15V, V_{CE}=600V, I_c=20A)

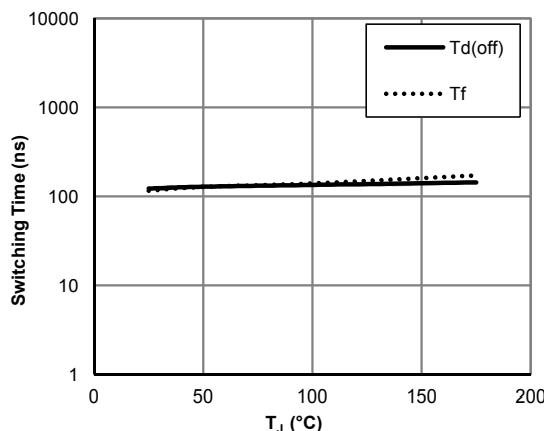


Figure 14: Switching Time vs. T_j
(V_{GE}=15V, V_{CE}=600V, I_c=20A, R_g=15Ω)

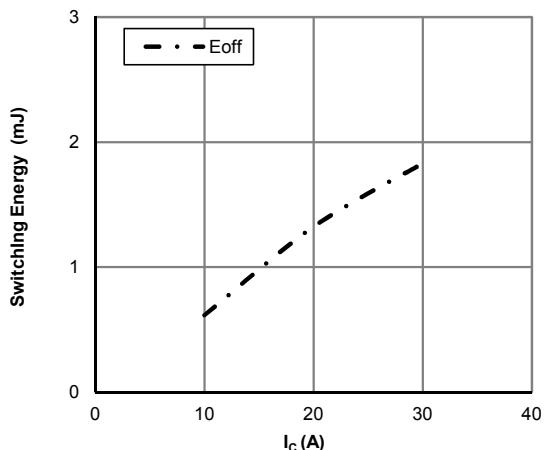
TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS


Figure 15: Switching Loss vs. I_c
 $(T_j=175^\circ\text{C}, V_{GE}=15\text{V}, V_{CE}=600\text{V}, R_g=15\Omega)$

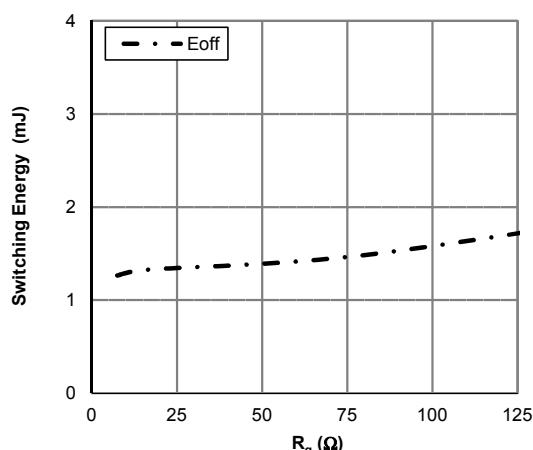


Figure 16: Switching Loss vs. R_g
 $(T_j=175^\circ\text{C}, V_{GE}=15\text{V}, V_{CE}=600\text{V}, I_c=20\text{A})$

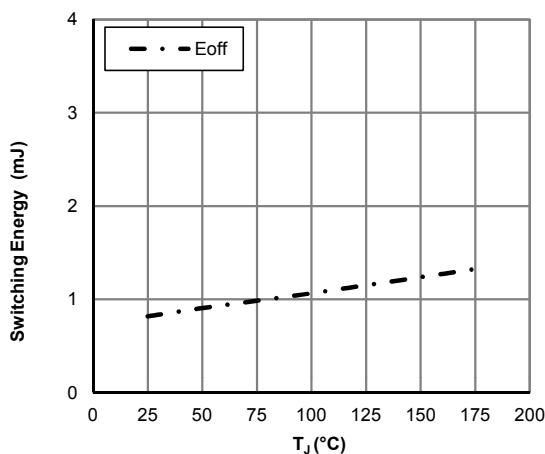


Figure 17: Switching Loss vs. T_j
 $(V_{GE}=15\text{V}, V_{CE}=600\text{V}, I_c=20\text{A}, R_g=15\Omega)$

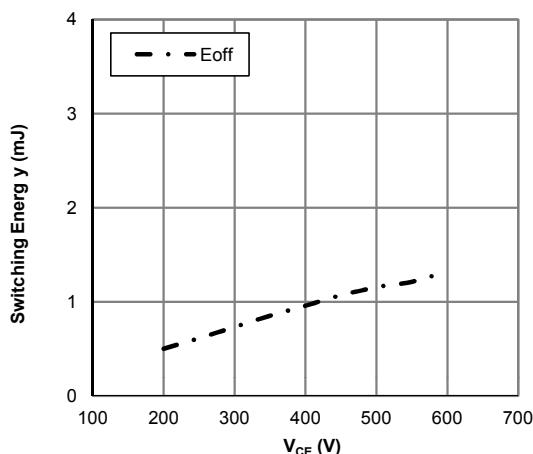


Figure 18: Switching Loss vs. V_{CE}
 $(T_j=175^\circ\text{C}, V_{GE}=15\text{V}, I_c=20\text{A}, R_g=15\Omega)$

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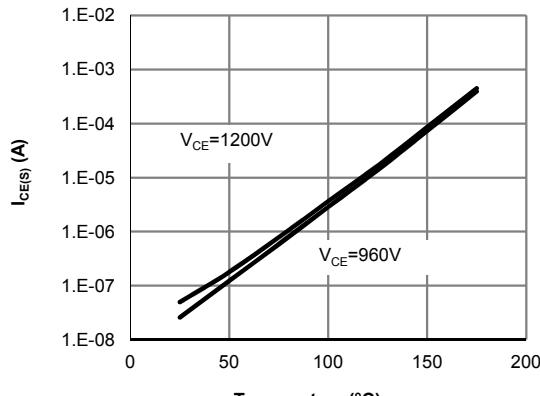


Figure 19: Diode Reverse Leakage Current vs.
Junction Temperature

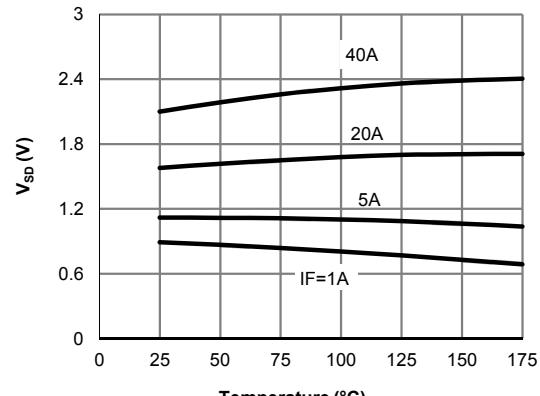


Figure 20: Diode Forward voltage vs. Junction
Temperature

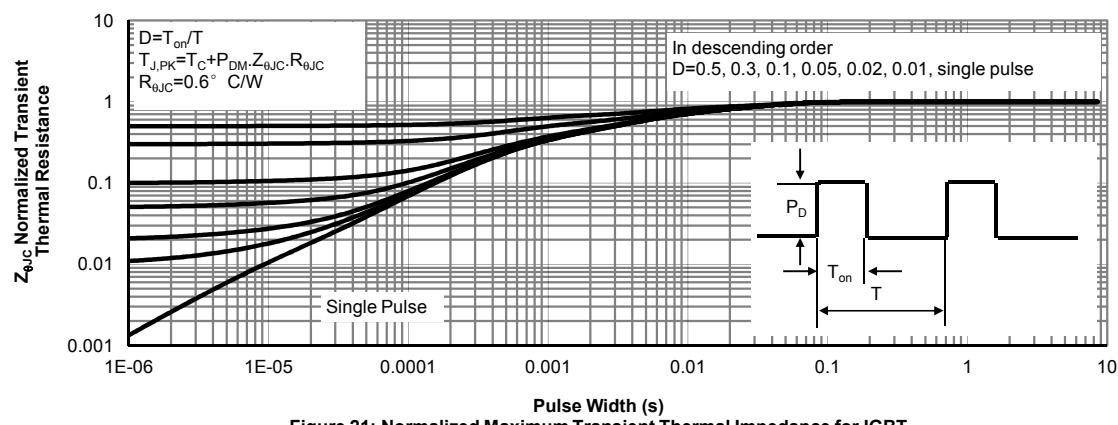


Figure 21: Normalized Maximum Transient Thermal Impedance for IGBT

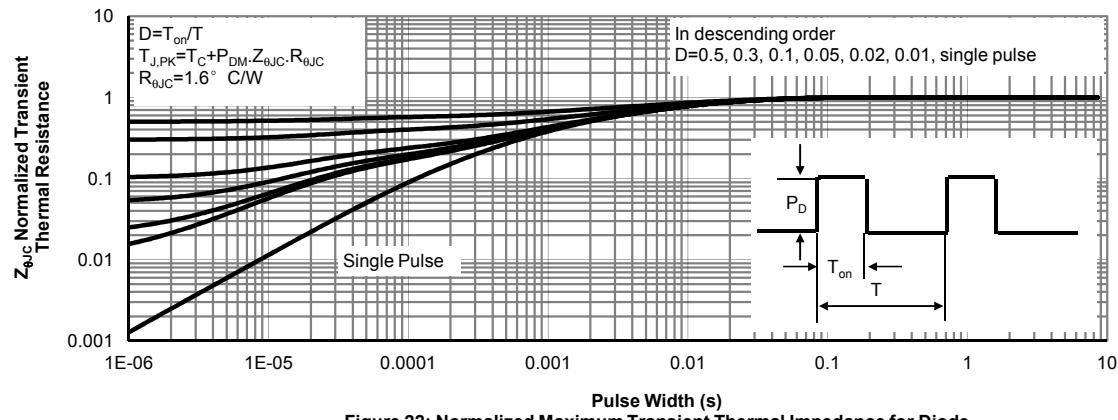


Figure 22: Normalized Maximum Transient Thermal Impedance for Diode

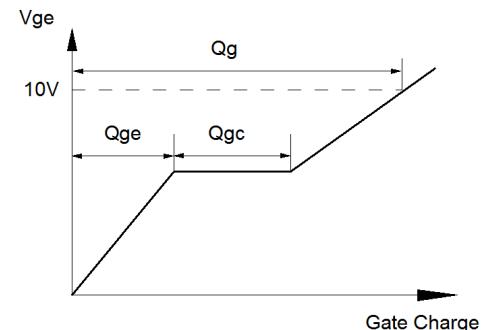
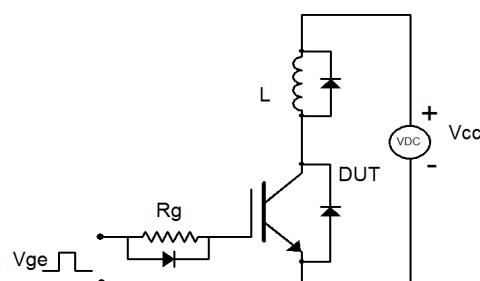


Figure A: Gate Charge Test Circuit & Waveforms

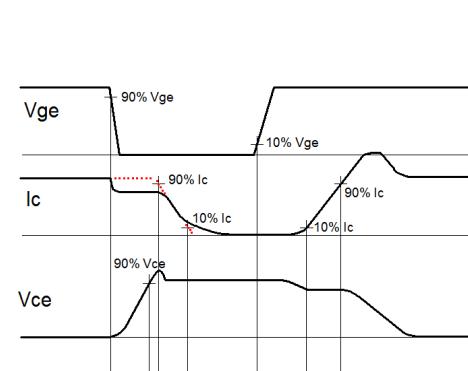
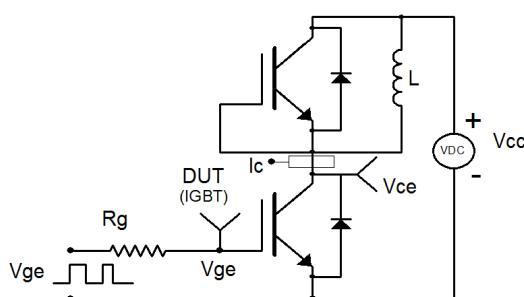


Figure B: Inductive Switching Test Circuit & Waveforms

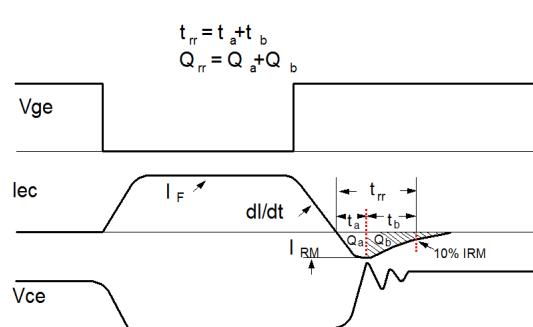
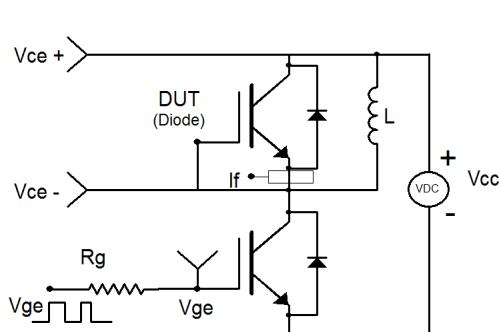


Figure C: Diode Recovery Test Circuit & Waveforms